

## N -Channel Enhancement Mode Power MOSFET

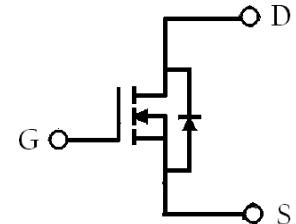
### Features:

- Low Gate Charge
- Simple Drive Requirement
- Pb-free lead plating package

TO-252(DPAK)



$BV_{DSS}$		200V
$I_D @ V_{GS}=10V$		25A
$R_{DS(on)(TYP)}$	$V_{GS}=10V, I_D=11A$	52m $\Omega$
	$V_{GS}=4.5V, I_D=5A$	52m $\Omega$



G : Gate      D : Drain  
 S : Source

### Ordering Information

Device	Package	Shipping
KJA55N20	TO-252 (Pb-free lead plating and halogen-free package)	2500 pcs / Tape & Reel

### Absolute Maximum Ratings (T<sub>C</sub>=25°C, unless otherwise noted)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V <sub>DS</sub>	200	V
Gate-Source Voltage	V <sub>GS</sub>	±20	
Continuous Drain Current @ T <sub>C</sub> =25°C, V <sub>GS</sub> =10V	I <sub>D</sub>	25	A
Continuous Drain Current @ T <sub>C</sub> =100°C, V <sub>GS</sub> =10V	I <sub>D</sub>	17.7	
Pulsed Drain Current *1	I <sub>DM</sub>	60	
Avalanche Current	I <sub>AS</sub>	20	mJ
Avalanche Energy @ L=1.6mH, I <sub>D</sub> =20A, R <sub>G</sub> =25Ω	E <sub>AS</sub>	320	
Repetitive Avalanche Energy@ L=0.1mH (Note 2)	E <sub>AR</sub>	4.6	
Total Power Dissipation @T <sub>C</sub> =25°C	P <sub>d</sub>	107	W
Total Power Dissipation @T <sub>A</sub> =25°C		1.14	
Operating Junction and Storage Temperature Range	T <sub>j</sub> , T <sub>stg</sub>	-55~+175	°C

Note : \*1. Pulse width limited by maximum junction temperature

\*2. Duty cycle ≤ 1%

### Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	R <sub>th,j-c</sub>	1.4	°C/W
Thermal Resistance, Junction-to-ambient, max	R <sub>th,j-a</sub>	110	°C/W

### Characteristics (T<sub>C</sub>=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
<b>Static</b>					
BV <sub>DSS</sub>	200	-	-	V	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA
V <sub>GS(th)</sub>	0.5	0.8	1.5	V	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA
I <sub>GSS</sub>	-	-	±100	nA	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V
I <sub>DSS</sub>	-	-	1	μA	V <sub>DS</sub> =200V, V <sub>GS</sub> =0V
	-	-	25		V <sub>DS</sub> =160V, V <sub>GS</sub> =0V, T <sub>j</sub> =125°C
R <sub>D(S(ON))</sub> *1	-	52	62	mΩ	V <sub>GS</sub> =10V, I <sub>D</sub> =11A
	-	52	70		V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A
G <sub>FS</sub> *1	-	40	-	S	V <sub>DS</sub> =15V, I <sub>D</sub> =11A
<b>Dynamic</b>					
Q <sub>g</sub> *1, 2	-	100	-	nC	V <sub>DS</sub> =160V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V
Q <sub>gs</sub> *1, 2	-	8.6	-		
Q <sub>gd</sub> *1, 2	-	18.4	-		
t <sub>d(ON)</sub> *1, 2	-	16.8	-	ns	V <sub>DS</sub> =100V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V, R <sub>G</sub> =25Ω
t <sub>r</sub> *1, 2	-	51	-		
t <sub>d(OFF)</sub> *1, 2	-	528	-		
t <sub>f</sub> *1, 2	-	309	-		

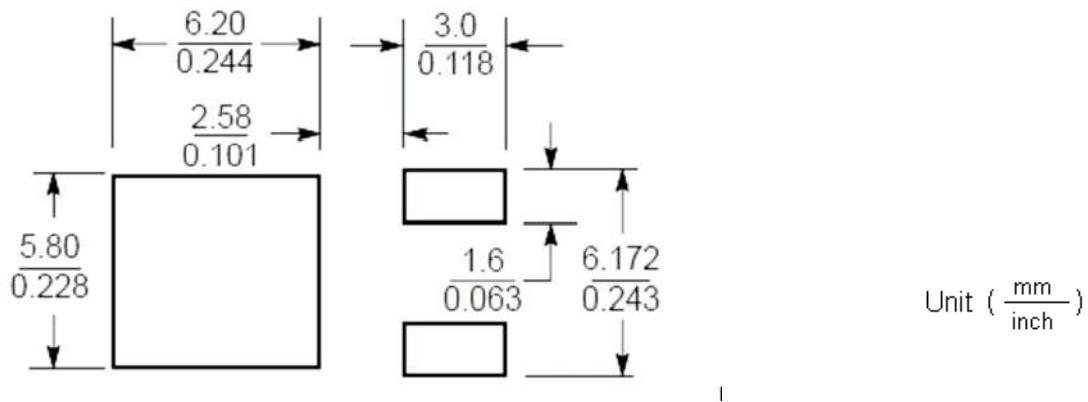
C <sub>iss</sub>	-	4260	-	pF	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V, f=1MHz
C <sub>oss</sub>	-	207	-		
C <sub>rss</sub>	-	172	-		
R <sub>g</sub>	-	1.2	-	Ω	f=1MHz
<b>Source-Drain Diode</b>					
I <sub>s</sub> *1	-	-	25	A	
I <sub>SM</sub> *3	-	-	60		
V <sub>SD</sub> *1	-	0.82	1.3	V	I <sub>F</sub> =20A, V <sub>GS</sub> =0V
t <sub>rr</sub>	-	93	-	ns	I <sub>F</sub> =20A, dI <sub>F</sub> /dt=100A/μs
Q <sub>rr</sub>	-	399	-	nC	

Note : \*1.Pulse Test : Pulse Width≤300μs, Duty Cycle≤2%

\*2.Independent of operating temperature

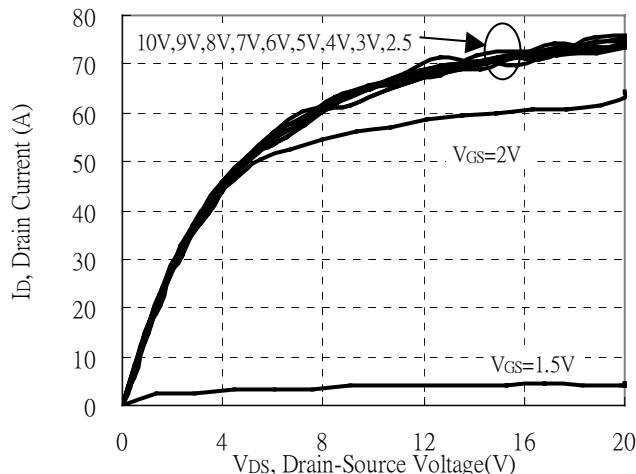
\*3.Pulse width limited by maximum junction temperature.

### Recommended soldering footprint

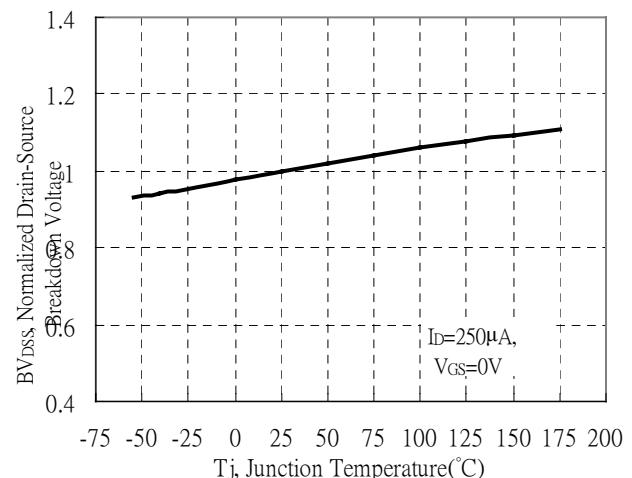


## Typical Characteristics

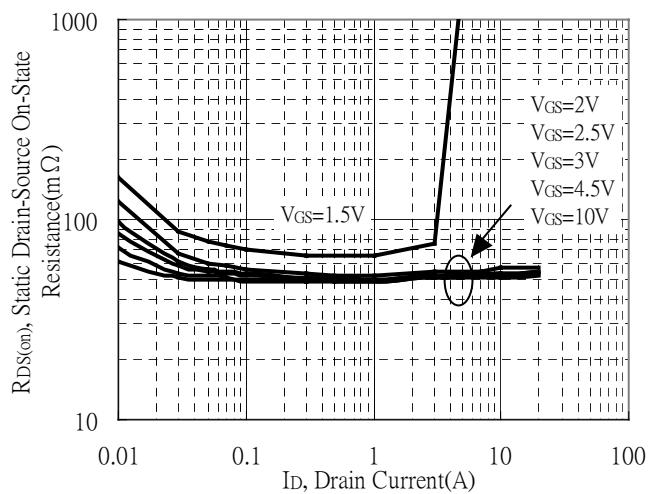
Typical Output Characteristics



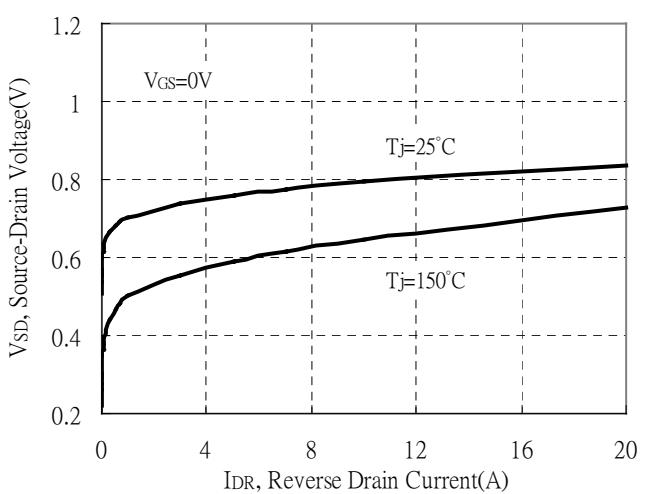
Breakdown Voltage vs Ambient Temperature



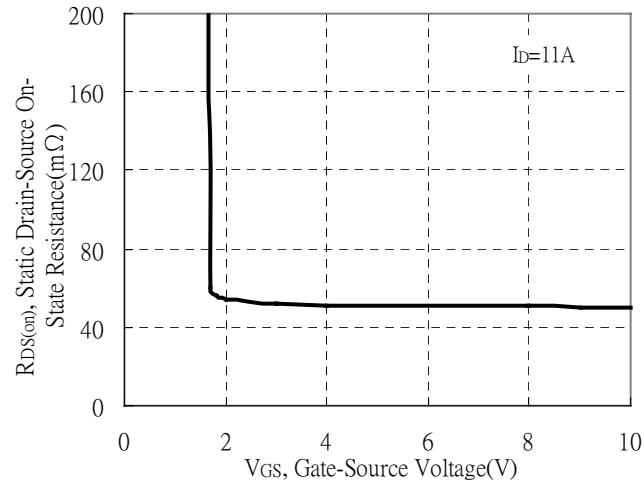
Static Drain-Source On-State resistance vs Drain Current



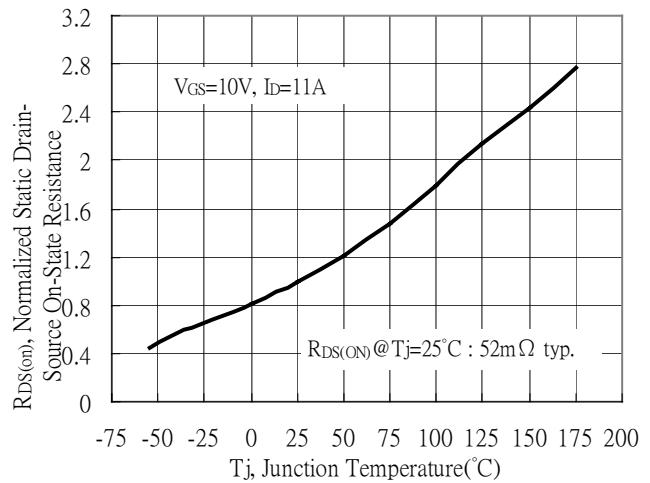
Reverse Drain Current vs Source-Drain Voltage



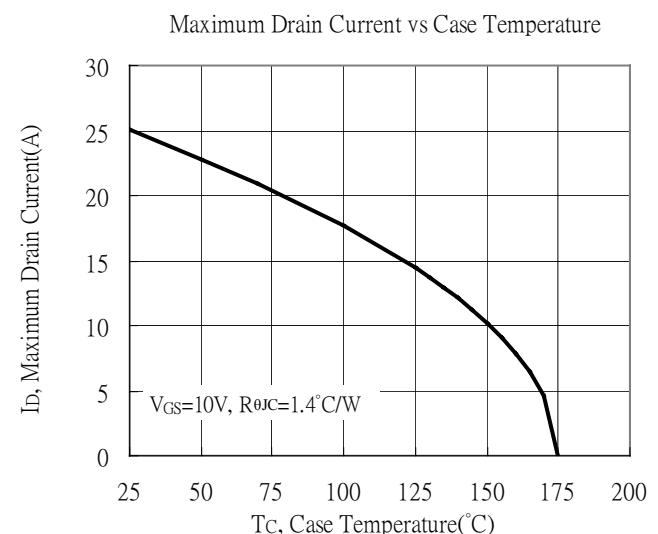
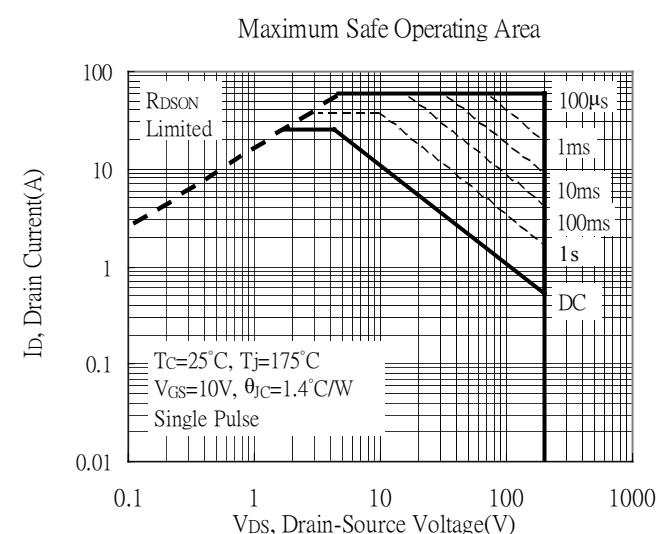
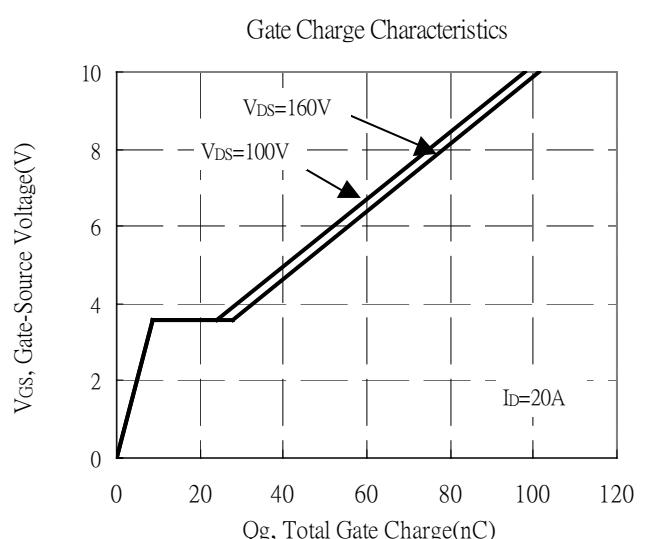
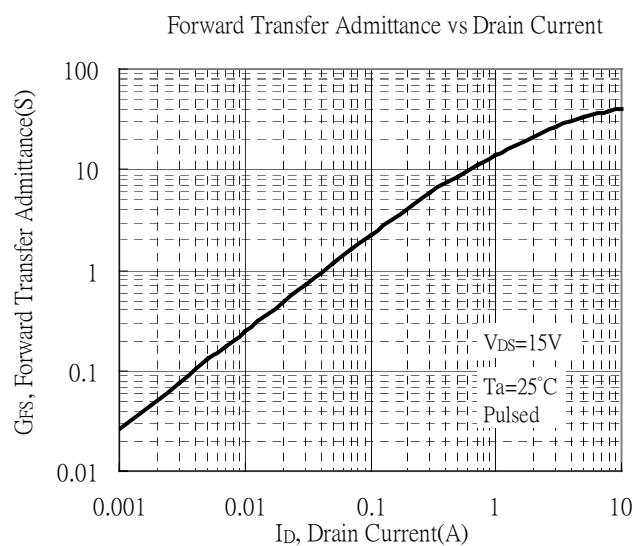
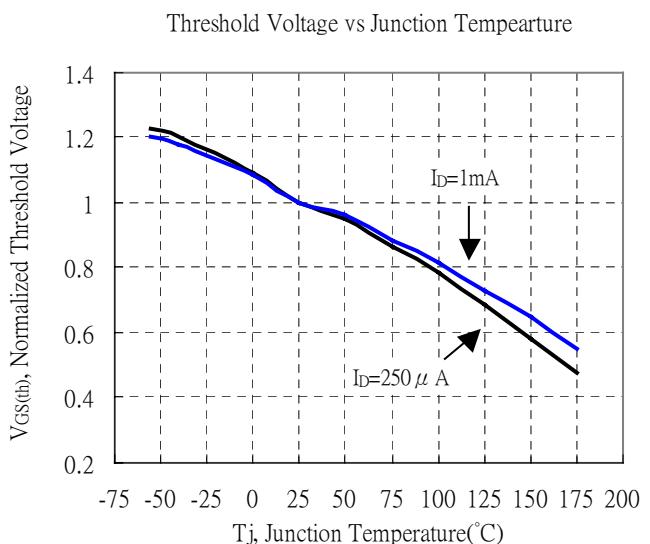
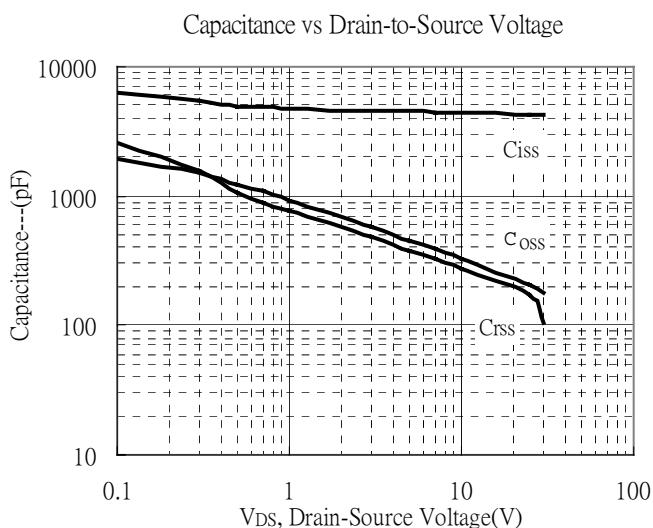
Static Drain-Source On-State Resistance vs Gate-Source Voltage



Drain-Source On-State Resistance vs Junction Temperature

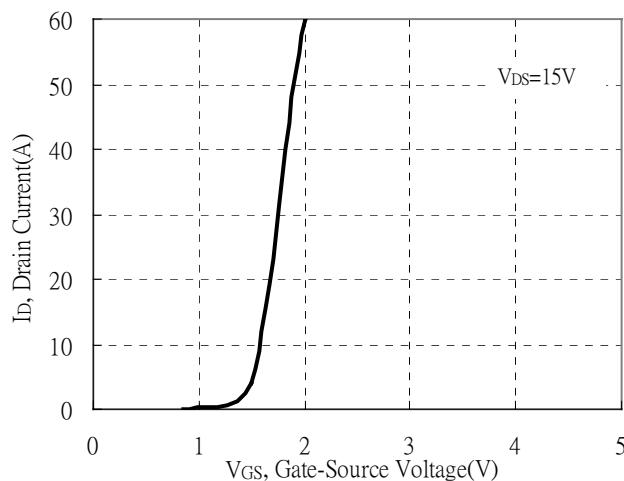


## Typical Characteristics(Cont.)

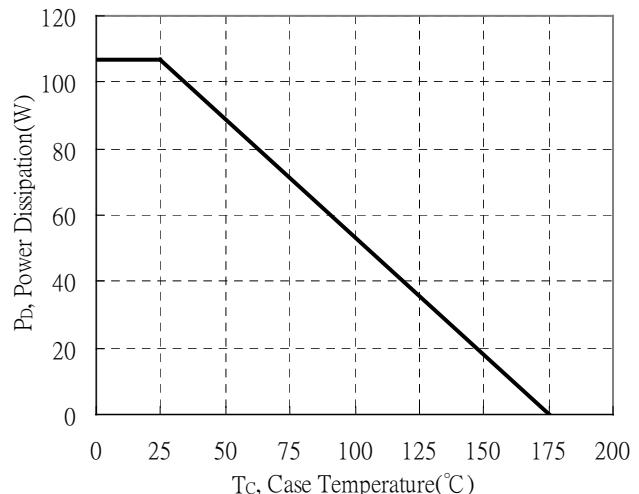


## Typical Characteristics(Cont.)

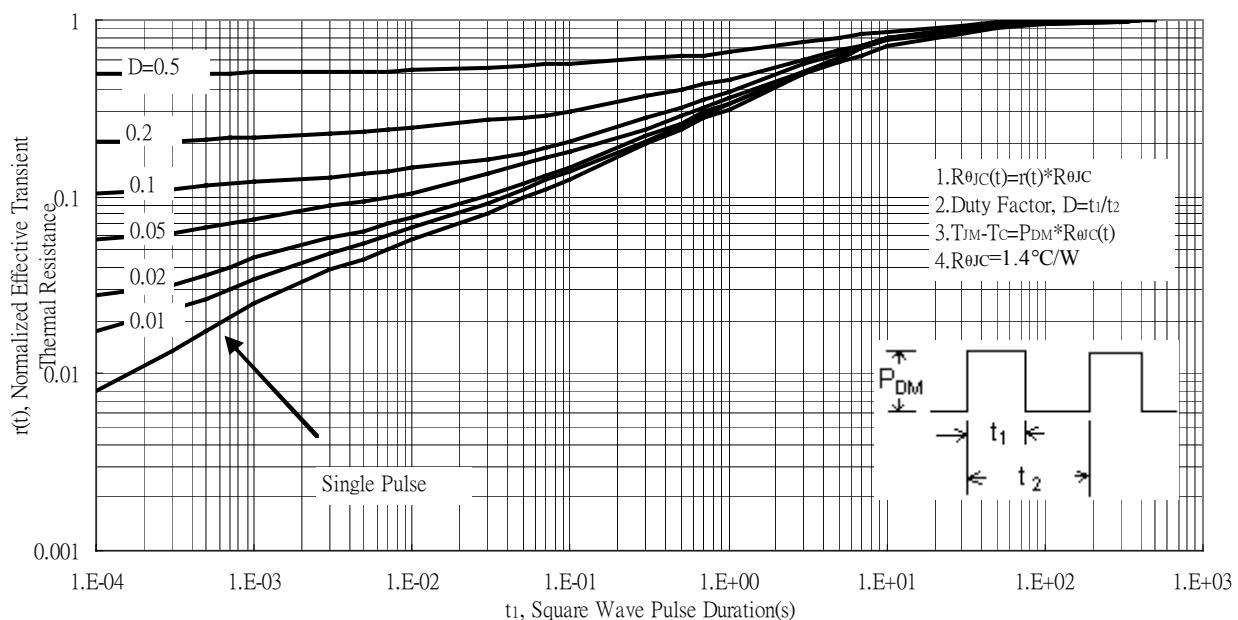
Typical Transfer Characteristics



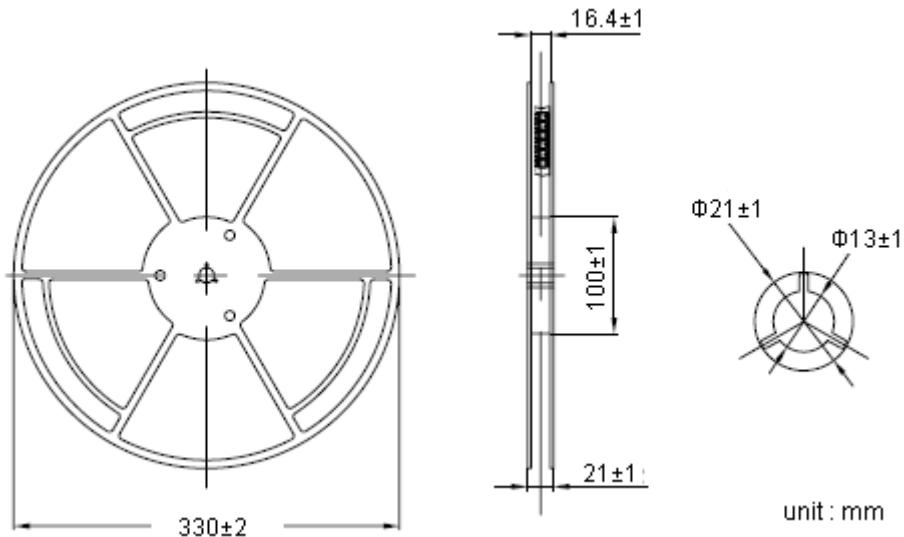
Power Derating Curve



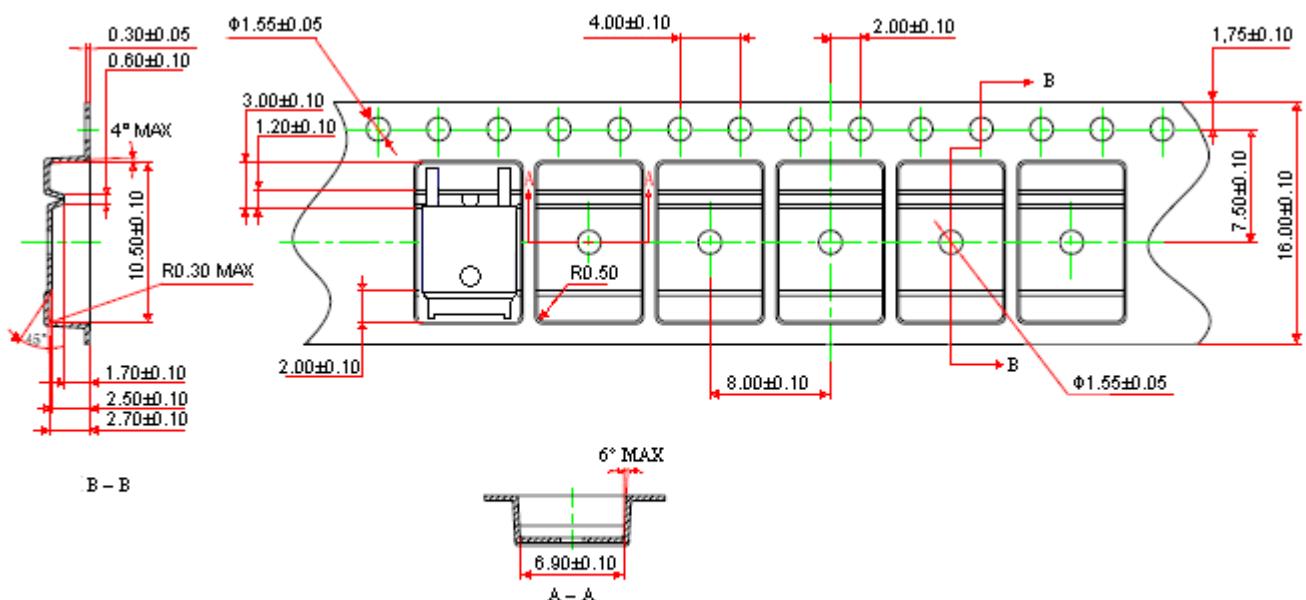
Transient Thermal Response Curves



## Reel Dimension



## Carrier Tape Dimension

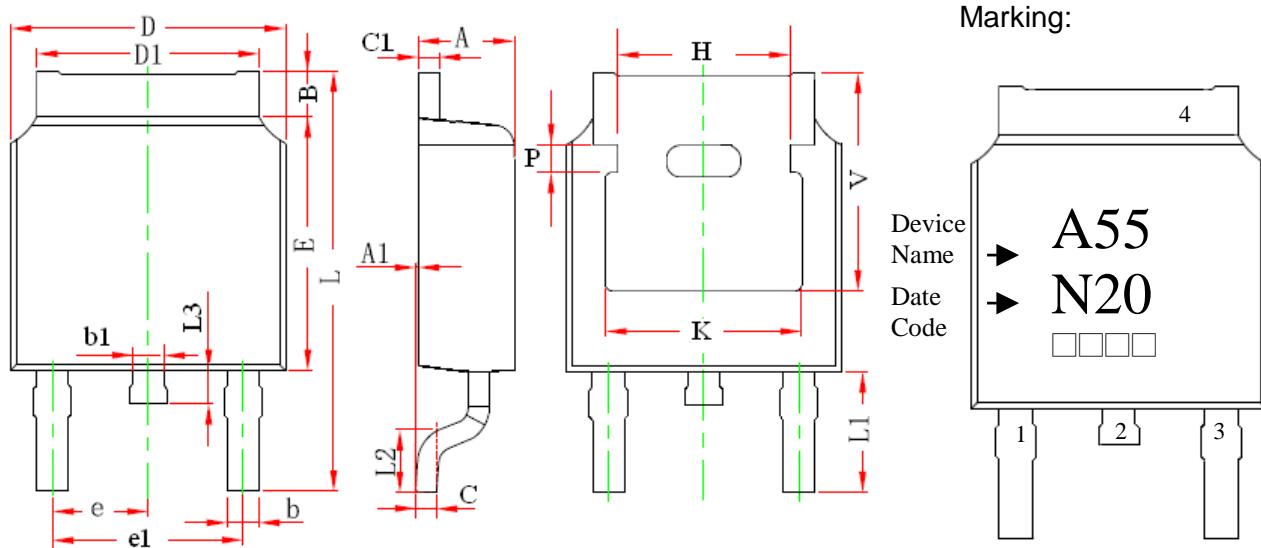


Notes:

1. 10 sprocket hole pitch cumulative tolerance  $\pm 0.2$ .
2. Camber not to exceed 1mm in 100mm.
3. Material: conductive black polystyrene, antistatic coated :  $10^5 \Omega/\square \sim 10^{11} \Omega/\square$

unit : mm

## TO-252 Dimension



3-Lead TO-252 Plastic Surface Mount Package

Style: Pin 1.Gate 2.Drain 3.Source  
4.Drain

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.087	0.094	2.200	2.400	e	0.086	0.094	2.186	2.386
A1	0.000	0.005	0.000	0.127	e1	0.172	0.188	4.372	4.772
B	0.039	0.048	0.990	1.210	H	0.163	REF	4.140	REF
b	0.026	0.034	0.660	0.860	K	0.190	REF	4.830	REF
b1	0.026	0.034	0.660	0.860	L	0.386	0.409	9.800	10.400
C	0.018	0.023	0.460	0.580	L1	0.114	REF	2.900	REF
C1	0.018	0.023	0.460	0.580	L2	0.055	0.067	1.400	1.700
D	0.256	0.264	6.500	6.700	L3	0.024	0.039	0.600	1.000
D1	0.201	0.215	5.100	5.460	P	0.026	REF	0.650	REF
E	0.236	0.244	6.000	6.200	V	0.211	REF	5.350	REF